# MA21D35

## Silicon epitaxial planar type

For rectification

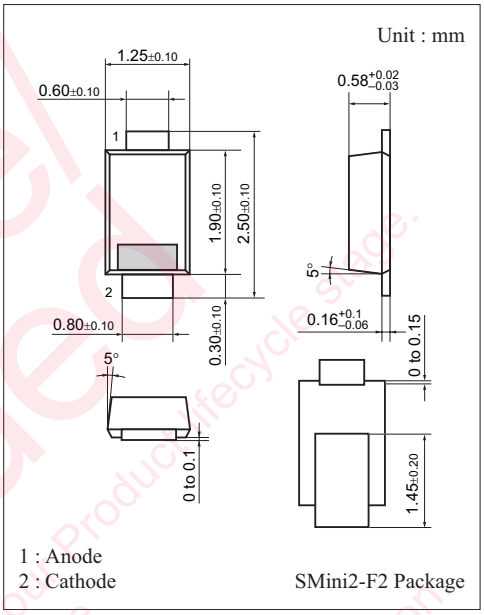
### ■ Features

- Forward current (Average) $I_{F(AV)}$ = 1.0 A rectification is possible
- Low reverse current $I_R$

### ■ Absolute Maximum Ratings $T_a$ = 25°C

| Parameter | Symbol | Rating | Unit |
|---|---|---|---|
| Reverse voltage | $V_R$ | 30 | V |
| Maximum peak reverse voltage | $V_{RM}$ | 30 | V |
| Forward current (Average) | $I_{F(AV)}$ | 1.0 | A |
| Non-repetitive peak forward surge current * | $I_{FSM}$ | 20 | A |
| Junction temperature | $T_j$ | 150 | °C |
| Storage temperature | $T_{stg}$ | –55 to +150 | °C |

Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)




Marking Symbol: 4W

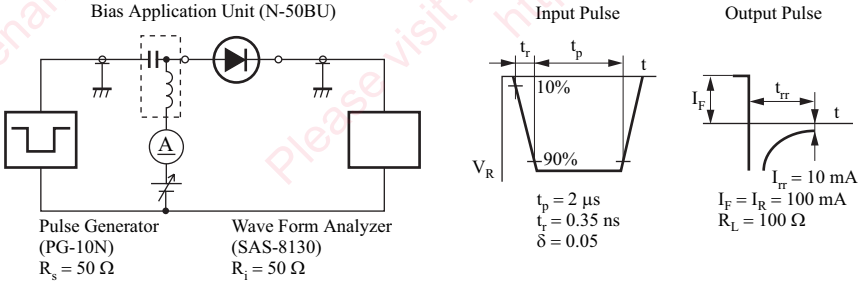
### ■ Electrical Characteristics $T_a$ = 25°C±3°C

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| Forward voltage | $V_{F1}$ | $I_F$ = 0.7 A | | 0.42 | 0.47 | V |
| | $V_{F2}$ | $I_F$ = 1.0 A | | 0.44 | 0.49 | |
| Reverse current | $I_R$ | $V_R$ = 30 V | | | 40 | μA |
| Terminal capacitance | $C_t$ | $V_R$ = 10 V, f = 1 MHz | | 43 | | pF |
| Reverse recovery time * | $t_{rr}$ | $I_F = I_R$ = 100 mA, $I_{rr}$ = 10 mA, $R_L$ = 100 Ω | | 13 | | ns |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. *: $t_{rr}$ measurement circuit



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(6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.